Defect investigation in irradiated ATLAS18 ITk Strip Sensors using

transient spectroscopy techniques

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Abstract

With the upgrade of the LHC to the High-Luminosity LHC (HL-LHC), the Inner Detector will be replaced with the new all-silicon ATLAS Inner Tracker (ITk). Comprising an active area of 165m², the outer detector layers will host strip modules, built with single-sided micro-strip sensors. The ATLAS18 main sensors were tested at different institutes in the collaboration for mechanical and electrical compliance with technical specifications, while technological parameters were verified on test structures from the same wafers before and after irradiation.

Diodes fabricated as test structures were studied using variants of Deep-Level Transient Spectroscopy (DLTS). Irradiated diode samples were measured with Current-DLTS, using both electrical and photo-induced injection. Utilising DLTS spectra with varying test parameters, trap energy levels and cross-sections associated with defects were obtained. This was done to improve the precision of sensor simulations as well as to compile a more complete model of radiation damage in ITk Strip Sensors. Moreover, previously observed features such as an increasing trend in the full depletion voltage after irradiation and little beneficial annealing in charge collection after high fluence irradiation of high energy protons were also investigated. This poster will present a summary of the defect parameters observed in the samples and will compare results obtained for samples with radiation damage from different sources at various fluences.

Samples

- □ diced MD8 diodes (8mm × 8mm) from irradiated QA pieces
- □ samples mounted on heatsinks, biased through backplane and wire-bonded implant; additional wire-bonded GR contact
- □ all samples were annealed for 80min @60°C

Sourc

previously observed unusual annealing effects of samples from IRRAD (see I. Mandic's talk at VCI2025)

е	Fluence [1 MeV n _{eq} /cm ²]		
	1 57011		





Deep-l	evel ⁻	Fransient Spect	roscopy	(DLTS)
				()

Principles of DLTS measurements:

- 1. DUT is under constant reverse bias
- 2. filling pulse with specific voltage V_P and duration is applied
 - V_P reduced reverse bias → majority carrier traps (holes)
 - V_P slight forward bias → minority carrier traps (electrons)
 - if capture rate much larger than competing majority traps)
- 3. bias back to prior level, measure transients
 - capacitance or current transients, depending on sample
- usually average O(100) transients per temperature point
- \Box plot ΔC or ΔI vs. temperature for fixed rate window corresponding to emission rate
- \Box analysing spectrum for varying rate window $[t_1; t_2]$ yields Arrhenius plot of trap levels





Hole trap hole injectior 1. Quiescent reverse bias \



electron trap

hiah iniection

. Quiescent reverse bias V











Photo-Induced Current Transient Spectroscopy (PICTS):

- Photo-Induced Current Transient Spectroscopy variant of basic DLTS/I-DLTS
 - trap concentration in irradiated diodes too high
 - for electrical filling and capacitance DLTS
- □ use LED for injection and trap filling
- IR-LED (1050nm) has high penetration depth, energy slightly above Si bandgap
- □ LED pulse allows charge injection above what is possible with (forward) electrical
- filling pulse; more/different traps can be saturated
- Can also use differential mode to subtract baseline current





DLTS spectra and Arrhenius plots

- trap filling purely through LED
 - second transient without LED to subtract baseline current
- observable defects even at low temperatures
 - not seen in without LED filling pulses
- convolution of two trap states in large peak
 - same large double-peak 200K/240K for all samples, irrespective of fluence or source
 - minor differences in low-temperature peaks



□ 240K peak corresponds to both electron and hole trap,

spectrum for specific rate window [t₁; t₂] corresponding to trap emission rate (Rate Window plot)

 V_{P}



- double-peak 200K/240K has highest trap concentration and energy closest to mid-bandgap
 - traps closer to midgap have most significant effect on behaviour
- □ CYRIC samples have higher trap concentration
- PICTS does not inherently differentiate between electron and hole
 - traps, unlike capacitance transients in DLTS
 - check whether electron/hole trap using UV-LED

⇒ charge generation at surface, only holes fill traps in depleted region

Φ [n _{eq} /cm²]	T _{peak} [K]	E _T [meV]	σ [cm²]
	200	/13 + 9	$2.3 \times 10^{-13} + 1.7X$

Field strength and filling pulse width dependence

- derive emission rate and transient amplitude from direct fit of transient at peak in spectrum
- □ field strength dependence of emission rate indicates whether defect acquires net charge upon emission

⇒ evidence of Poole-Frenkel effect, defect is electron-donor



□ measurement of transient amplitude with increasing filling pulse width allows for fitting of various capture processes ⇒ indicates nature of defect in crystal lattice, e.g. point defect or dislocation





0.01

all other traps are electron traps

- electron capture coefficient much higher in 240K peak
- complimentary energy levels add up to Si bandgap



	1 = 7 - 1 / 1	200	110 = 0	
С	4.57014	240	427 ± 19	6.7 x 10 ⁻¹⁵ ± 2.5X
	8.34e14	200	400 ± 9	$1.1 \times 10^{-13} \pm 1.7 X$
		240	459 ± 13	3.8 x 10 ⁻¹⁴ ± 1.9X
	1 54015	200	340 ± 11	2.6 x 10 ⁻¹⁵ ± 1.8X
D	2.6014	240	396 ± 15	1.5 x 10 ⁻¹⁵ ± 2.0X
		200	403 ± 5	$1.8 \times 10^{-13} \pm 1.3 X$
	3.6014	240	475 ± 10	8.8 x 10 ⁻¹⁴ ± 1.6X
	4.2e14	200	395 ± 9	$1.0 \times 10^{-13} \pm 1.7X$
		240	454 ± 14	$3.1 \times 10^{-14} \pm 2.0 X$
	7.6e14	200	385 ± 14	4.1 x 10 ⁻¹⁴ ± 2.3X
		240	460 ± 23	4.5 x 10 ⁻¹⁴ ± 3.1X
	1 2015	200	388 ± 9	5.4 x 10 ⁻¹⁴ ± 1.7X
	1.2015	240	469 ± 13	6.8 x 10 ⁻¹⁴ ± 1.9X

<u></u>
1E-3 0
, pulse width [s]
0

Conclusions

- multiple microscopic defects were observed in ITk Strip Sensor diode samples after irradiation with low and high energy protons
 - trap parameters were determined, and most traps were found to be electron traps in the upper half of the bandgap
 - no clear dependence on fluence and proton source were observed for the investigated samples
- investigation will continue with neutron/gamma-irradiated samples and different levels of annealing

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